What is Claimed is:

[c1]   A computerized method of calculating a custom die price, comprising:

providing an interface for designating base parameters;

selecting a base die based on the base parameters;

creating a reference die based on a design methodology and the base
parameters;

calculating a complexity factor based on designated custom parameters
and the reference die; and

calculating the custom die price based on the base die, the custom
parameters and the complexity factor.

[c2]   The method of claim 1, wherein the base parameters include a technology, an
X-dimension, a Y-dimension and a number of levels of metal.

[c3]   The method of claim 1, wherein the selecting step includes:

providing a set of possible base dies based on the designated chip
parameters; and selecting the base die from the set of possible base dies.

[c4]   The method of claim 1, wherein the reference die is a most complex die
available based on the designated base parameters.

[c5]   The method of claim 1, wherein the custom parameters include a core, an oxide
level, a solder type, a cell logic circuit count, register array parameters and
memory parameters.

[c6]   The method of claim 1, wherein the calculating a complexity factor step
includes:

creating a custom die having the base parameters and the custom
parameters;

determining a custom die yield;

determining
a reference die yield; and

dividing the custom die yield by the reference die yield to provide the
complexity factor.

[c7]   The method of claim 1, wherein the calculating the custom die price step

includes:

    calculating a base die price for the base die;

    providing the custom die price by modifying the base die price based on the custom parameters; and

    adjusting the custom die price using the complexity factor.

[c8]   The method of claim 1, further comprising calculating a chip price based on the custom die price and designated package parameters.

[c9]   The method of claim 8, further comprising:

    designating a chip quantity; and

    adjusting the chip price based on the chip quantity.

[c10]   A computerized method of calculating a custom die price, comprising:

    designating base parameters;

    calculating a base die price based on the base parameters;

    creating a reference die based on a design methodology and the base parameters;

    creating a custom die by designating custom parameters;

    calculating a complexity factor based on the custom die and the reference die; and

    calculating the custom die price based on the base die price, the custom die and the complexity factor.

[c11]   The method of claim 10, wherein the designating step includes:

    providing a set of possible base dies; and

    selecting a base die from the set of possible base dies.

[c12]   The method of claim 11, wherein the designating step further includes selecting a first base parameter, wherein each possible base die includes the first base parameter.

[c13]   The method of claim 10, wherein the calculating a complexity factor step includes:

    determining a custom die yield based on the custom die;

    determining a reference die yield based on the reference die; and

dividing the custom die yield by the reference die yield to provide the complexity factor.

[c14]   The method of claim 10, wherein the calculating the custom die price step includes:

modifying the base die price based on the custom parameters to provide the custom die price; and

adjusting the custom die price using the complexity factor.

[c15]   The method of claim 10, further comprising calculating a chip price based on the custom die price and designated package parameters.

[c16]   The method of claim 15, further comprising:

designating a chip quantity; and

adjusting the chip price based on the chip quantity.

[c17]   A system for determining a custom die price, comprising:

a base die system for designating base parameters;

a reference die system for creating a reference die based on the base parameters and a design methodology;

a custom die system for designating custom parameters;

a complexity system for calculating a complexity factor based on the custom parameters and the reference die; and

a calculation system for calculating the custom die price based on the base parameters, the custom parameters and the complexity factor.

[c18]   The system of claim 17, further comprising a packaging system for calculating a chip price based on the custom die price and designated packaging parameters.

[c19]   The system of claim 18, further comprising a volume system for adjusting the chip price based on a designated quantity.

[c20]

A computer program product comprising a computer useable medium having computer readable program code embodied therein for determining a custom die price, the program product comprising:

program code for designating base parameters;

program code for calculating a base die price based on the base parameters;

program code for creating a reference die based on a design methodology and the base parameters;

program code for creating a custom die by designating custom parameters;

program code for calculating a complexity factor based on the custom die and the reference die; and

program code for calculating a custom die price based on the base die price, the custom die and the complexity factor.

[c21]   The computer program product of claim 20, wherein the program code for designating base parameters includes:

program code for providing a set of possible base dies; and

program code for selecting a base die from the set of possible base dies.

[c22]   The computer program product of claim 21, wherein the program code for designating base parameters further includes program code for selecting a first base parameter, wherein each possible base die includes the first base parameter.

[c23]   The computer program product of claim 20, wherein the program code for calculating a complexity factor includes:

program code for determining a custom die yield based on the custom die; and

program code for determining a reference die yield based on the reference die.

[c24]   The computer program product of claim 20, wherein the program code for calculating a custom die price includes:

program code for calculating a custom die price for the custom die using the base die price and the custom die; and

program code for adjusting the custom die price using the complexity factor.

[c25]   The computer program product of claim 20, further comprising program code for calculating a chip price based on the custom die price and designated package parameters.

[c26]   The computer program product of claim 20, further comprising:

program code for providing an interface for designating a chip quantity; and

program code for adjusting the chip price based on the chip quantity.